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2SC1567, 2SC1567A

Silicon NPN epitaxial planar type

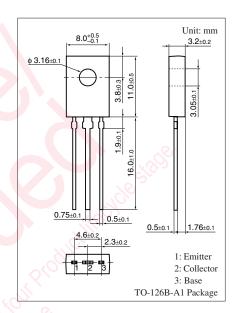
For low-frequency high power driver Complementary to 2SA0794, 2SA0794A

■ Features

- ullet High collector-emitter voltage (Base open) V_{CEO}
- Optimum for the driver stage of low-frequency and 40 W to 100 W output amplifier
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SC1567	V_{CBO}	100	V
(Emitter open)	2SC1567A		120	
Collector-emitter voltage	2SC1567	V _{CEO}	100	V
(Base open)	2SC1567A		120	
Emitter-base voltage (Coll	V _{EBO}	5	V .	
Collector current	I_{C}	0.5	A	
Peak collector current	I_{CP}	1	A	
Collector power dissipation	P _C	1.2	S W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



■ Electrical Characteristics T_a = 25°C ± 3°C

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SC1567	V _{CEO}	$I_C = 100 \mu\text{A}, I_B = 0$	100			V
(Base open)	2SC1567A		will soil	120			
Emitter-base voltage (Colle	ctor open)	V _{EBO}	$I_E = 1 \mu A, I_C = 0$	5			V
Forward current transfer rat	io	h _{FE1} *	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$	130		330	_
Nall.		h _{FE2}	$V_{CE} = 5 \text{ V}, I_{C} = 500 \text{ mA}$	50	100		
Collector-emitter saturation	voltage	V _{CE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.2	0.4	V
Base-emitter saturation volt	age	V _{BE(sat)}	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.85	1.20	V
Transition frequency		f_T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance		C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		11	20	pF
(Common base, input open	circuited)						

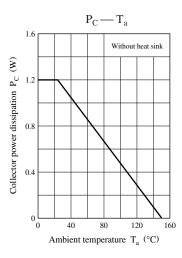
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

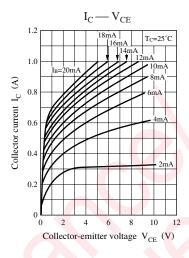
2. *: Rank classification

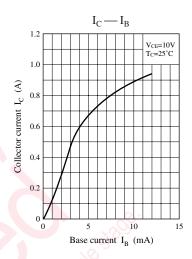
Rank	R	S
$h_{\rm FE1}$	130 to 220	185 to 330

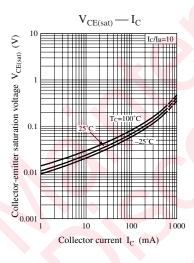
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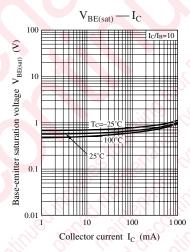
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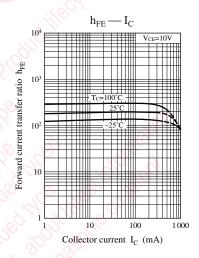


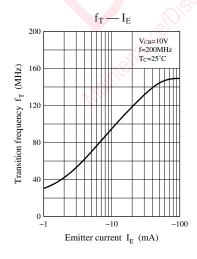


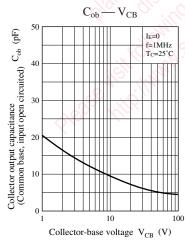


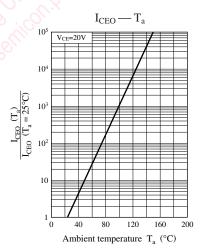






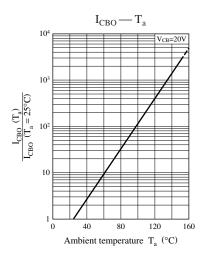


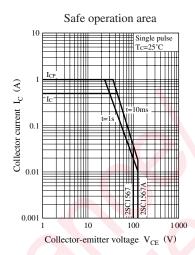




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